

REPLY UNDER 37 C.F.R § 1.116 – EXPEDITED PROCEDURE – ART UNIT 2827

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A circuit package for an electronic device, comprising:
a first circuit board positioned in a first plane;
a second circuit board positioned in a second plane;
at least one brace coupled to the first circuit board and the second circuit board;
at least two electrically conductive leads extending from at least one surface of the circuit package; and
a housing formed between the first and second circuit boards ~~and configured to~~
substantially that covers at least one surface of each circuit board and leaves another surface of each circuit board substantially uncovered to thereby expose the uncovered surface to an environment exterior of the circuit package,
wherein the housing includes an external surface that is flush with the uncovered surfaces of each circuit board.
2. (Previously Presented) The circuit package of Claim 1, wherein the housing comprises a bottom surface that includes a cavity formed therein.
3. (Previously Presented) The circuit package of Claim 1, wherein the first and second circuit boards are each made of a single-sided direct bonded copper substrate.
4. (Currently Amended) The circuit package of Claim 1, wherein the brace comprises:
an elongate body;
at least two arm portions extending from the body at least one of the arm portions coupled to the first circuit board and another of the arm portions coupled to the second circuit board; and
at least two leg portions extending from the body each leg portion operable to function as a flexible spacer between the first and second circuit boards.
5. (Previously Presented) The circuit package of Claim 1, wherein the circuit package comprises a first brace and a second brace, each brace positioned between the first and second

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circuit boards and coupling the first circuit board to the second circuit board, the first and second braces are operable to function as a flexible spacer between the first and second circuit boards.

6. (Previously Presented) The circuit package of Claim 1, further comprising:
a plurality of electrically conductive leads adapted to mount the circuit package on an external surface, and configured to support the circuit package in an upright position relative to the external surface.
7. (Canceled).
8. (Original) The circuit package of Claim 1, wherein the housing is made from an injected molded plastic.
9. (Previously Presented) The circuit package of Claim 1, further comprising:
an H-bridge circuit mounted on at least one of the first and second circuit boards.
10. (Presently Amended) The circuit package of Claim [7] 2, wherein the H-bridge circuit comprises:
a first leg including a first lead and a first output node, and a first switch coupled therebetween;
a second leg including a second lead and a second output node, and a second switch coupled therebetween;
a third leg including the first lead and the second output node, and a third switch coupled therebetween;
a fourth leg including the second lead and the first output node, and a fourth switch coupled therebetween.
11. (Previously Presented) A circuit package for an electronic device, comprising:
a first circuit board positioned in a first plane;
a second circuit board positioned in a second plane and in contact with the first circuit board;
at least one brace coupled to the first circuit board and the second circuit board;

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a plurality of electrically conductive leads extending from the circuit package and adapted to mount the circuit package on an external surface; and
a housing formed to surround at least a portion of the first and second circuit boards.

12. (Previously Presented) The circuit package of Claim 11, wherein the housing forms a surface between at least two electrically conductive leads of the circuit package, wherein the surface of the circuit package comprises a cavity formed therein.
13. (Original) The circuit package of Claim 11, wherein the first and second circuit boards are made of a single-sided direct bonded copper substrate.
14. (Presently Amended) The circuit package of Claim 11, wherein the brace is an electrical conductor.
15. (Original) The circuit package of Claim 11, wherein the housing is made from an injected molded plastic.
16. (Previously Presented) The circuit package of Claim 11, further comprising:
an H-bridge circuit mounted on at least one of the first and second circuit boards.
17. (Previously Presented) The circuit package of Claim 16, wherein the H-bridge circuit comprises:
a first leg including a first lead and a first output node, and a first switch coupled therebetween;
a second leg including a second lead and a second output node, and a second switch coupled therebetween;
a third leg including the first lead and the second output node, and a third switch coupled therebetween;
a fourth leg including the second lead and the first output node, and a fourth switch coupled therebetween.

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18. (Currently Amended) A method of manufacturing a circuit package comprising the steps of:
- positioning a first circuit board in a first plane;
 - positioning a second circuit board in a second plane;
 - coupling at least two brace members to the first ~~circuit board to the~~ and second circuit boards;
 - mounting at least two electrically conductive leads to at least one of the first and second circuit boards; and
 - injecting a molding material between the first and second circuit boards to form a housing that substantially covers at least one surface of each of the circuit boards and leaves another surface of each circuit board substantially uncovered to thereby expose at least one surface of the first and second circuit boards.
19. (Currently Amended) The method of Claim 18, further comprising the step of:
- coupling a the plurality of conductive leads to the first and second circuit boards.
20. (Previously Presented) The circuit package of Claim 11, further comprising:
- a plurality of components mounted on the first and second circuit boards in a region that is surrounded by the housing.